



# SOT1573-2(SC)

HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, step-cut wettable flank, 0.8 mm pitch, 4 mm x 4 mm x 1.98 mm body

4 March 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HQFN16
<b>Package style descriptive code</b>	HQFN (thermal enhanced quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	05-02-2021
<b>Manufacturer package code</b>	98ASA01738D

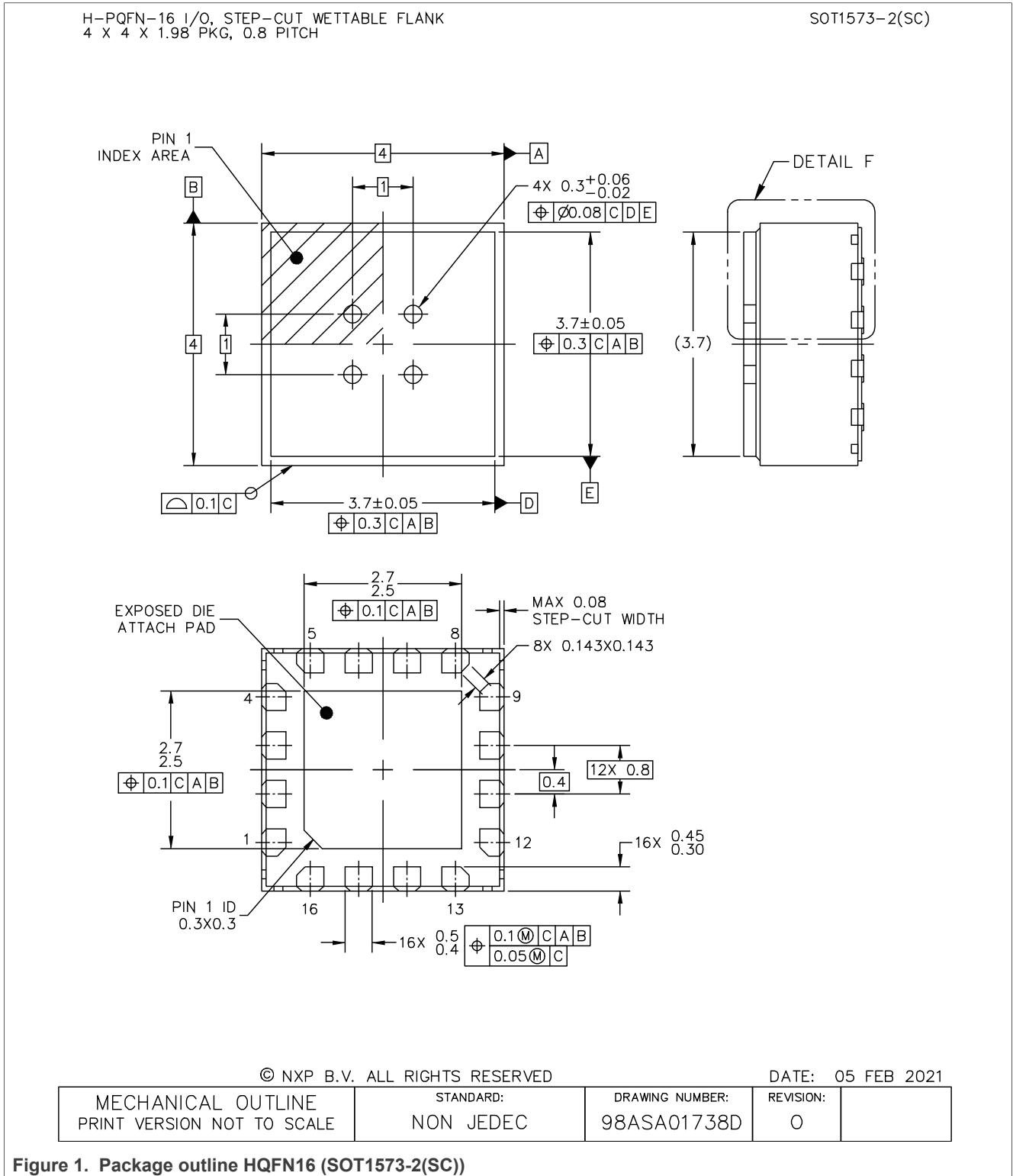
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
package height	1.88	1.98	2.08	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	16	-	

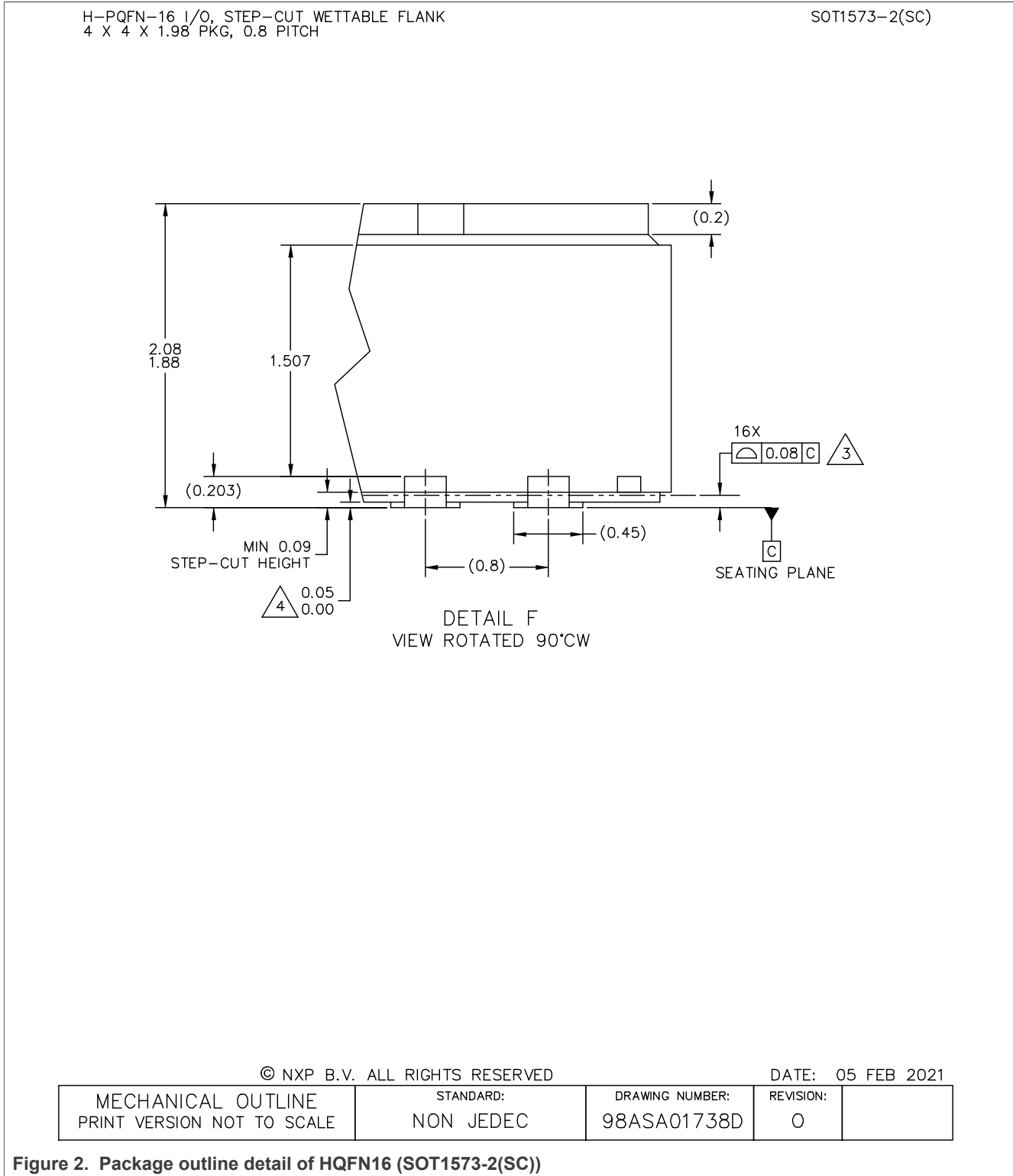


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2 Package outline

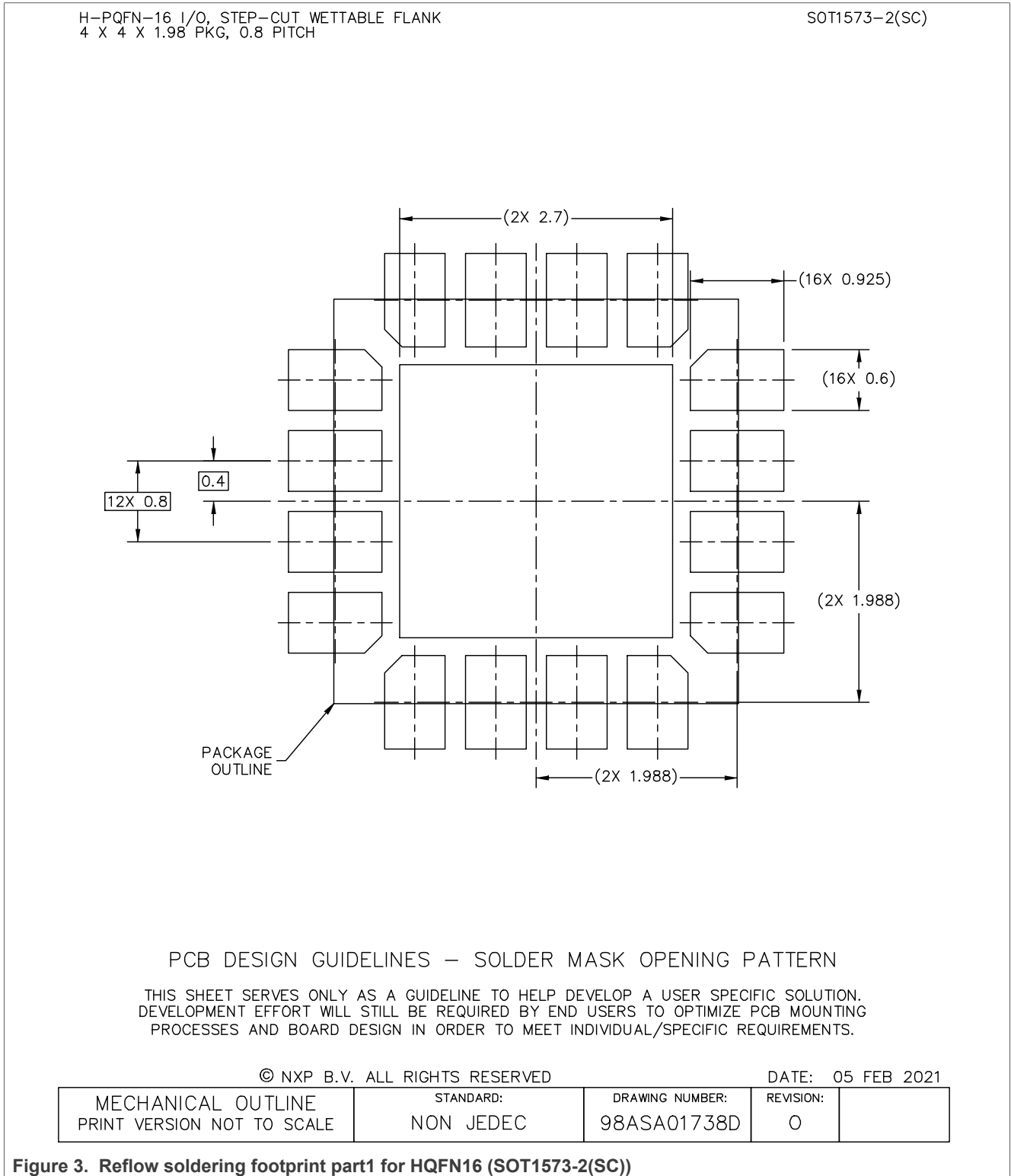


HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, step-cut wettable flank, 0.8 mm pitch, 4 mm x 4 mm x 1.98 mm body

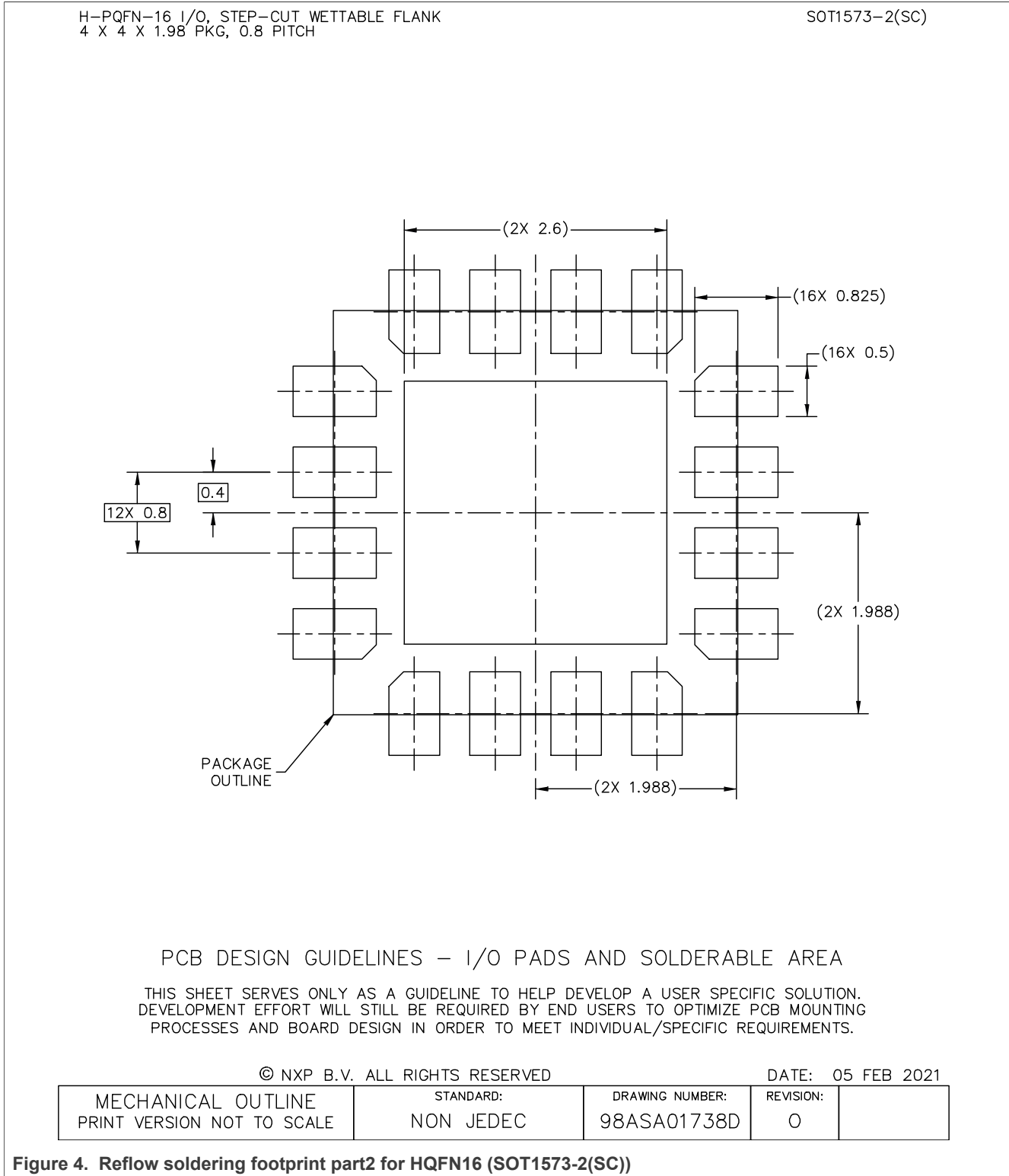


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3 Soldering



HQFN16, thermal enhanced quad flat package, no leads, 16 terminals, step-cut wettable flank, 0.8 mm pitch, 4 mm x 4 mm x 1.98 mm body



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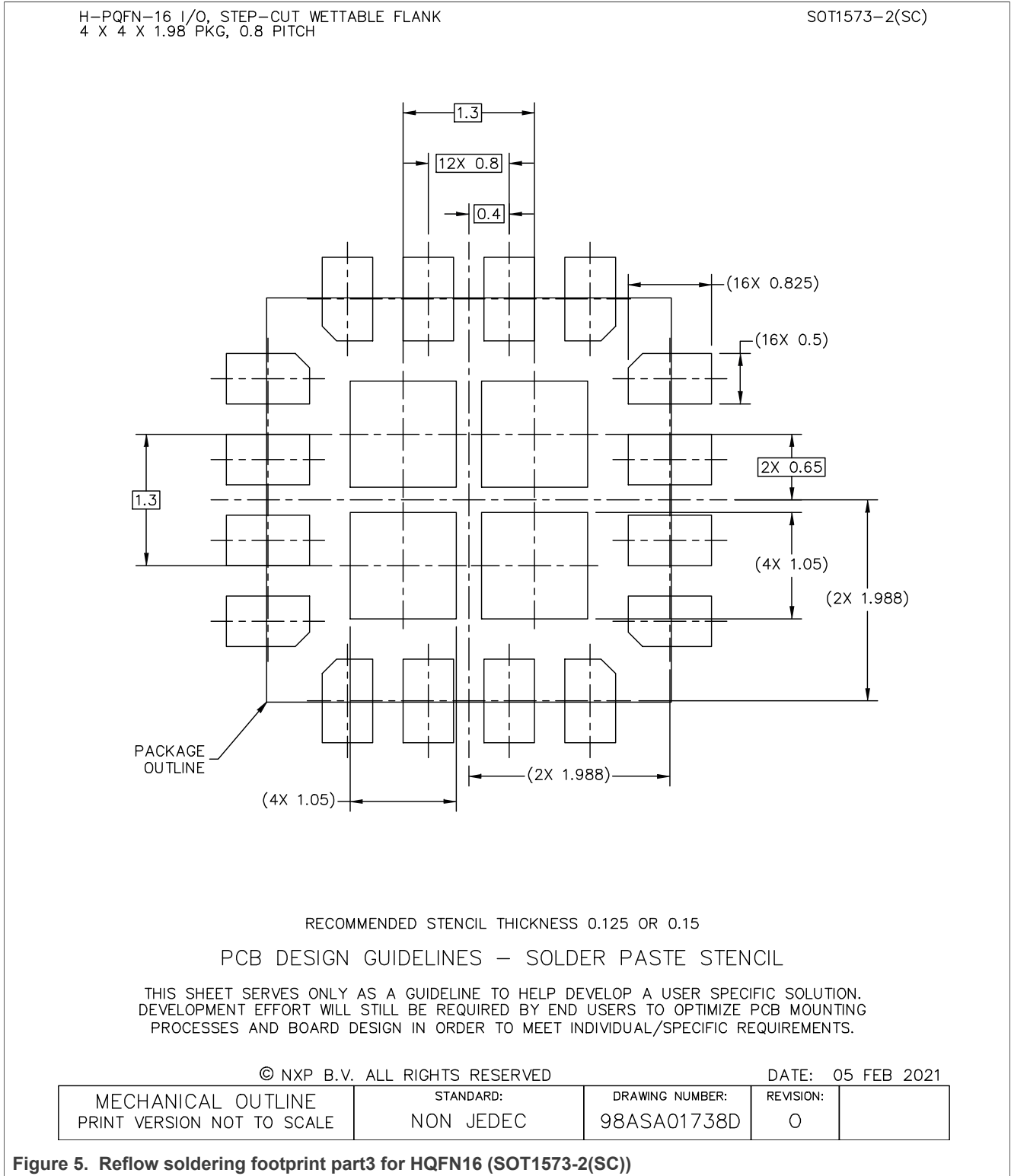


Figure 5. Reflow soldering footprint part3 for HQFN16 (SOT1573-2(SC))

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H-PQFN-16 I/O, STEP-CUT WETTABLE FLANK  
4 X 4 X 1.98 PKG, 0.8 PITCH

SOT1573-2(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
4. DIMENSION APPLIES ONLY FOR TERMINALS.
5. MIN METAL GAP SHOULD BE 0.2 MM.

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DATE: 05 FEB 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01738D	REVISION: 0	
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Figure 6. Package outline note HQFN16 (SOT1573-2(SC))

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## 4 Legal information

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**Contents**

---

1 Package summary .....1  
2 Package outline .....2  
3 Soldering .....4  
4 Legal information .....8